Title of the Invention: Chemical Mechanical Abrasive Composition for Use in Semiconductor Processing

Abstract of the Disclosure

The invention provides a chemical mechanical abrasive composition for use in semiconductor processing, which comprises phosphorous acid and/or a salt thereof as an abrasive enhancer. The chemical mechanical abrasive composition of the invention can be in the form of a slurry which comprises 70-99.5% by weight of an aqueous medium, 0.1-25% by weight of an abrasive, and 0.01-2% by weight of said abrasion enhancer. The chemical mechanical abrasive composition of the invention may further comprise an abrasion co-enhancer selected from an amino acid, a salt thereof, a carboxylic acid, a salt thereof, or a mixture of the acids and/or salts.